



NOTES: UNLESS OTHERWISE SPECIFIED

- PERFORM WIRE BONDING USING TOOLING TF-XXX-XX-XX, WIREBOND FIXTURE.
- CLEAN HANDLING: VENDOR SHALL HANDLE USING ANTI-STATIC AND CLEAN ROOM METHODS AND PACKAGE CIRCUIT BOARD IN ANTI-STATIC BAG LABELED WITH PART NUMBER AND REVISION SHOWING. AFTER ASSEMBLY WRAP IN ANTI-STATIC BAG AND FOIL.

CONTACT TIMOTHY KNIGHT NELSON, SLAC, (650) 926-2274,TKNELSON@SLAC.STANFORD.EDU, FOR INFORMATION ON THESE COMPONENTS.

ITEM	STOCK OR PART NO	TITLE OR DESCRIPTION	QTY
4	PF-XXX-XXX-XX	KAPTON FILM .05 MM THK	1
3	PF-XXX-XXX-XX	EPOXY GLASS LAMINATE NEMA GRADE G-10	2
2	SA-XXX-XXX-XX	SILICON BIOXIDE	2
1	PF-XXX-XXX-XX	CARBON FIBER K13C2U	1

SA-XXX-XXX-XX	DIMENSIONING AND TOLERANCING IS IAW ASME Y14.5M-1994 AND Y14.41-2003	SCALE: 1:1 DO NOT SCALE DRAWING	CAD FILE NAME: SILICON DETECTOR MODULE.dft
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES: BREAK EDGES .005-.015 INTERNAL CORNERS R.015 MAX FRACTIONS ± --- DEC .XX± .01 .XXX± .005 .XXXX± --- ANGLE ± .5		<b>SLAC</b> NATIONAL ACCELERATOR LABORATORY	<b>U.S. DEPARTMENT OF ENERGY</b>
NEXT ASSEMBLIES:	ALL SURF	THE DRAWINGS, SPECIFICATIONS AND OTHER DATA HEREIN PROVIDED SHALL NOT BE COPIED, PUBLISHED OR OTHERWISE FURTHER DISSEMINATED WITHOUT PRIOR WRITTEN PERMISSION OF STANFORD UNIVERSITY/SLAC	
		ENGR S. OSIER DWN S. OSIER CHKR T. NELSON	HPS 2014 LAYER 4-6 SILICON DETECTOR MODULE PROTOTYPE DRAWING NUMBER PF-XXX-XXX-XX REVISION NUMBER 0 D